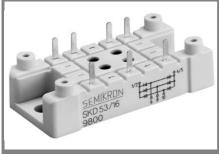
# **SKD 83**



**Power Bridge Rectifiers** 

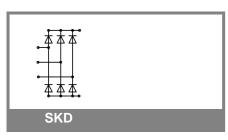
#### **SKD 83**

#### Features

- Glass passivated silicon chips
- Low thermal impedance through use of direct copper bonded aluminum substrate (DCB) base plate
- Blocking voltage up to 1800 V
- Suitable for PCB mounting and wave soldering
- For applications with high vibrations we recommend to fasten the bridge to the pcb with 4 selftapping screw

### **Typical Applications**

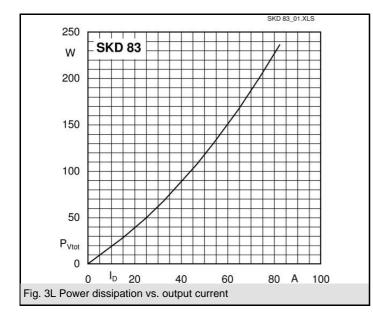
- Three phase rectifiers for power supplies
- Input rectifiers for variable frequency drives
- Rectifiers for DC motor field supplies
- Battery charger rectifiers
- 1) Freely suspended or mounted on an insulator
- Mounted on a painted metal sheet of min.
  250 x 250 x 1 mm
- 3)  $T_{solder} = 250 \pm 10 \ ^{\circ}C \ (10 \ s)$

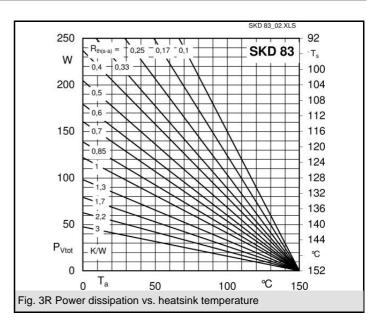


V <sub>RSM</sub>	V <sub>RRM</sub> , V <sub>DRM</sub>	I <sub>D</sub> = 83 A (full conduction)
V	V	(T <sub>s</sub> = 95 °C)
500	400	SKD 83/04
900	800	SKD 83/08
1300	1200	SKD 83/12
1600	1400	SKD 83/14
1700	1600	SKD 83/16
1900	1800	SKD 83/18

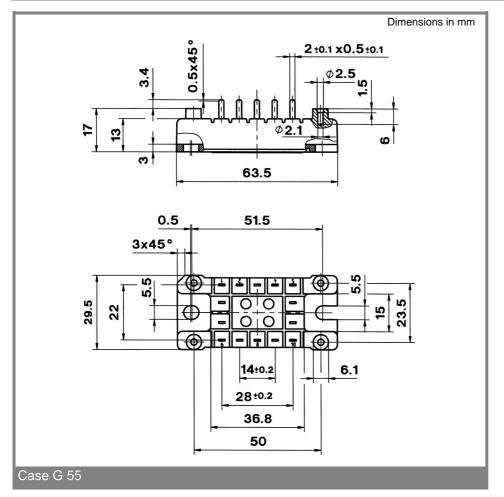
Symbol	Conditions	Values	Units
I <sub>D</sub>	T <sub>s</sub> = 95 °C	83	А
5	$T_a = 45 \text{ °C}; \text{ isolated } ^1)$	4	А
	$T_a = 45 \text{ °C}; \text{ chassis }^{2)}$	20	А
	T <sub>a</sub> = 45 °C; P5A/100 (R4A/120)	32 (34)	А
	T <sub>a</sub> = 35 °C; P1A/120F	83	А
I <sub>FSM</sub>	T <sub>vi</sub> = 25 °C; 10 ms	700	А
	T <sub>vi</sub> = 150 °C; 10 ms	560	А
i²t	T <sub>vj</sub> = 25 °C; 8,3 10 ms	2450	A²s
	T <sub>vj</sub> = 150 °C; 8,3 10 ms	1570	A²s
V <sub>F</sub>	T <sub>vi</sub> = 25 °C; I <sub>F</sub> = 80 A	max. 1,45	V
V <sub>(TO)</sub>	T <sub>vi</sub> = 150 °C	max. 0,8	V
r <sub>T</sub>	T <sub>vi</sub> = 150 °C	max. 7,5	mΩ
I <sub>RD</sub>	$T_{vj} = 25 \text{ °C}; V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$	max. 0,2	mA
	$T_{vj} = 150 \text{ °C}; V_{RD} = V_{RRM}$	4	mA
R <sub>th(j-s)</sub>	per diode	1,4	K/W
11(10)	total	0,233	K/W
R <sub>th(j-a)</sub>	isolated <sup>1)</sup>	14,83	K/W
	chassis <sup>2)</sup>	2,83	K/W
T <sub>vj</sub>		- 40 + 150	°C
T <sub>stg</sub>		- 40 + 125 <sup>3)</sup>	°C
V <sub>isol</sub>	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 ( 3000 )	V
Ms	to heatsink; SI units	2 ± 15 %	Nm
Mt			
a		5 * 9,81	m/s²
m		30	g
Case		G 55	

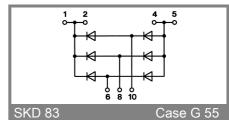
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